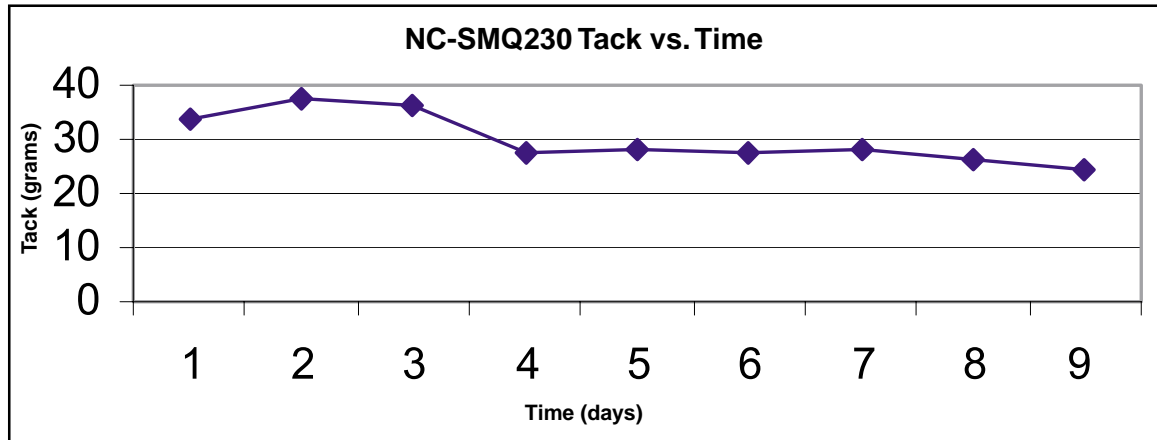




Tack vs. Time (static conditions)

This Tack vs. Time study was performed at Indium Corporation's Research & Development Facility. Tack measurements were taken daily over a four-day period on a Malcolm TK-1 Tackiness Tester per IPC-TM-650. 95.5Sn/3.8Ag/.7Cu alloy, -325+500 mesh, 89.3% metal load solder paste was used. 1/4" diameter paste deposits were printed on panels with a .006" stencil and stored at 76% relative humidity and 22°C.



Solder paste tack stability is an indication of minimal paste "dry-out" at room temperature, a solder paste property critical to achieving an efficient, profitable assembly process. This is especially true in high mix, low volume manufacturing facilities.

Results demonstrate NC-SMQ230's ability to maintain tack strength over a nine-day period.